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Document Number / Disk File:	By:	Current Rev:	Date:	
597-1001-01	Shane	0A	7/09/2009	
	McKinney			
Assemblies Covered:				
E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)				



Revision	Date	ECO #	Revised By	Description of Changes
0A			S.McKinney	Initial Release

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver
- Needle nose Pliers

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NOTE : Disconnect any AC Power Cords attached to the power supplies before disassembly of the unit.



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3.	 Removal of the Power Supply (ies) does not require any tools. a. Press and hold the green button towards the power supply handle. b. Pull the supply straight out of the rear of the chassis. c. Discard the Power Supply (ies) in the appropriate Recycling Bin. 				
4.	 Removal of the Remote Management Module (if present) requires a #2 Phillips screwdriver. a. Remove the two (2) screws securing the module to the rear of the chassis. b. Disconnect the module cable from the motherboard, and lift the module out of the chassis. 				

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				<u> </u>	
4.	 c. Remove the cable connective module. d. Remove the three (3) screated by securing the module brack the module. e. Discard the Remote Management Module, cabracket, and screws in the appropriate Recycling Experience bracket. 	ews ket to able, the			
5.	Removal of the PCI card assem not require any tools. a. Remove the PCI card by the assembly on either er two blue marks and lifting straight out of the chassis	holding nd of the it		PCI Card Assembly	
6.	 Removal of the PCI card (if instarequires a #2 Phillips screw drival a. Remove the PCI card from riser by pushing the blue the latch and swinging the open, removing the screw securing the card to the b flipping the rear card reta open, and pulling the PCI out away from the riser. b. Discard the PCI card an in the appropriate Recyber. 	rer. m the lever on e latch racket, iner card d screw		Screw Latch	

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E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)				

6.	Retainer	
7.	 Removal of the PCI riser card does not require a tool. a. Remove the PCI riser card from the bracket by pushing down on the blue bracket latch and sliding the riser card sideways towards the latch and then pulling straight up off the bracket. b. Discard the PCI riser card and bracket in the appropriate Recycling Bin. 	Latch
8.	 Removal of the Air Duct does not require any tools. a. Remove the Air Duct by lifting it straight up and out of the chassis. b. Discard the Air Duct in the appropriate Recycling Bin. 	Air Duct

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Assemi	E-2900 R2 (786-0156-0X, 7	86-0157-0	X, 786-0158-0X, 78	6-0159-0X)
9.	 Removal of the Battery Backup present) does not require any to a. Disconnect the battery cathe mid-plane. b. Slide the battery towards of the chassis about half and lift out of the chassis. c. Open the battery case, and disconnect the external cand the cable going from battery pack to the batter controller board. d. Discard the Battery Pack Controller Board, the Battery pack in the appropriate Recycling Figure 1000 and 10000 and 1000 and 10	the from the front an inch, nd able, the y k, the	Battery Backup	Battery Cable
9.0				
10.	Removal of the Air Baffles does require a tool. a. Pull directly up on each of baffles. b. Discard the Air Baffles i appropriate Recycling E	f the air n the		Air affles

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	E-2900 R2 (786-0156-0X, 7	86-0157-0	X, 786-0	158-0X, 786	6-0159-0X)
11.	 Removal of the Bridge Board do require any tools. a. Open the retention clips Bridge Board on the mid and motherboard. b. Pull the Bridge Board str to remove. c. Discard the Bridge Board the appropriate Recycl 	of the -plane, aight up ard in		ridge Board	
11.					
12.	 Removal of the Active (Redund Assembly does not require any a. Disconnect all fan power from the mid-plane. b. Carefully pick up the ass and remove straight up fa chassis. c. Fans can be lifted straigh the assembly. d. Discard the Fan Assem fans in the appropriate Recycling Bin 	tools. cables embly rom the nt out of ably and		Fan Power Connectors	

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			·	

12.		
13.	 Removal of the Passive (Non-Redundant) Fan Assembly does not require any tools. a. Disconnect all fan power cables from the mid-plane. b. Carefully pick up the assembly and remove straight up from the chassis. c. Fans can be lifted forward out of the assembly. d. Discard the Fan Assembly and fans in the appropriate Recycling Bin 	
13.		

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	E-290	0 R2 (786-0156-0X, 78	86-0157-0	X, 786-0	158-0X, 78	6-0159-0X)
14.	RAID Act any tools a. Pu RA DI b. Pu co c. Pu Ac of d. Di an	of the RAID Mini DIMM ivation Key does not re- ish the retaining clips of AID Mini DIMM away fr MM. Ill the DIMM away from nnector to remove. Ish the tabs to the side itivation Key and lift the its connector. scard the RAID Mini I d RAID Activation Ke propriate Recycling I	equire on the om the n the es of the e key out DIMM ey in the		Min DIM	and a second sec
15	requires a a. Re ac b. Re Ac c. Sli ba the ou d. Lif the e. Di an	of the Active Mid-Plan a #2 Philips screwdrive emoval of power conne- tive mid-plane. emove the screw secur- tive Mid-Plane to the c de the mid-plane to the c de the mid-plane towa ck of the chassis, mak e backplane contacts a t. e the mid-plane up and e chassis. scard the Active Mid- d screw in the appro- ecycling Bin.	er. ection to ing the chassis. rds the ing sure are fully d out of Plane	Charles of And		ower hection

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15.	Screw			
16.	 Removal of the Passive Mid-Plarequires a #2 Philips screwdrive a. Remove power connection passive mid-plane. b. Remove the screw securn Passive Mid-Plane to the chassis. c. Slide the mid-plane toware back of the chassis, make the backplane contacts are out. d. Lift the mid-plane up and the chassis. e. Discard the Active Midand screw in the approre Recycling Bin. 	er. on to ring the rds the ing sure are fully I out of -Plane		
16.	SATA Connections			

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17.	 All remaining cable connectors be disconnected. a. Disconnect all power cab the surrounding powers (the motherboard and one backplane). b. For passive system, rem SATA cables from mother cables from mother cable from 6th HDD option, remove power an cable from 6th HDD option and backplane. d. Discard all cables in the appropriate Recycling for the surrounding power of the surroun	oles from (three on e on the ove all erboard. HDD d data n card	8	ower ections		
17.	SATA Connections	No. 100	C	HDD able ections		
18.	 Removal of the CPU Heatsink(s) requires a #2 Philips screwdrive a. Start loosening the four (screws of each heatsink turns at a time in the order in the picture below. b. Once all screws are fully the heatsinks out of the constraints out of the constraints of the Heatsink(s) appropriate Recycling for the second second	er. 4) two er shown out, life chassis.) in the		Heatsink		

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20.	 Removal of the Memory DIMMs Lithium Battery from the mother do not require any tools. a. Remove each of the Mem DIMMs by pushing down on the two latches, one o end of the DIMM connect memory DIMM straight ou remove. b. Remove the coin style Lit Battery. c. Discard the Memory DII and Lithium Battery in t appropriate Recycling E *** CAUTION *** 	rboard hory and out n each tor. Lift ut to thium MMs the Bin. en		
21.				

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22.	 Removal of the Optical Drive (if requires a #2 Philips screwdrive a. Press the tab on the plast behind the backplane, and the drive straight out of the drive straight out of the chassis. b. For 2.5" drive enclosure, the two (2) screws secure blue tab to the rear of the c. In case of 3.5" drive encl the optical drive as an introduced that must be remo a CDROM carrier using a Philips screwdriver. d. Discard the Optical Drive Plastic guide, Drive Carlington and sin the appropriate Recy Bin. 	er. stic guide hd pull he remove ing the e drive. losure, terposer ved from a #2 ve, rrier, screws	Optical Drive 3.5 Enclosure		
22.			Optical Drive 2.5" Enclosure		

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E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)



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23.	 b. Remove the four (4) screase securing the drive to the (two on each side). (represent drive installed) c. Discard the Hard Driver Carriers, and screws in appropriate Recycling 	carrier eat for (s), the	-0	2.5" HI	
23.	3.5" HDD				
24.	 Removal of the Standard Control (SCP) (if present) requires a #2 screwdriver. a. For 3.5" HDD enclosure, the latch at the rear of the Standard Control Panel a it towards the front of the chassis. b. For 2.5" HDD enclosure, disconnect the two cable the midplane, press the I the rear of the SCP, and towards the front of the chassis. d. For 2.5" HDD enclosure, disconnect all cables from the standard control for the chassis. 	Philips press e and push s from atch at push it hassis.			SCP

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	 SCP. e. Remove the screw secur control board to the panel bracket. f. Press the panel bezel tak underside of the bezel brand pull the bezel off. g. Discard the Standard C Panel, control board, be panel bracket, and scree appropriate Recycling bracket. 	es on the racket, control ezel, ew in the				
24.	Latch on SCP	PROD_CODE_SRT		es on 2.5" osure SCP		
24.	2.5" Enclosure SCP			3.5"	Enclosure SCP	

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E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)

24.	Tabs	
25.	 Removal of the Local Control Panel (LCP) (if present) requires a #2 Philips screwdriver. a. Disconnect the two cables attached to the backplane. b. Press the latch towards the side of the chassis, and pull the panel out through the front (as shown in step 24). 	
25.	 c. Remove the screw on the rear of the panel assembly. d. Disconnect and remove the cables from the controller board and LCD. e. Remove the screw from the controller board and pull out of the assembly. f. Remove the two screws from the LCD and pull out of the assembly 	Cables on 3.5" Enclosure LCP

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25.	 g. Press in the two bezel cli the bottom of the panel a and pull off the bezel. h. Discard the LCD, brack controller board, cables screws in the appropria Recycling Bin. 	ets, s, and		a Tabs	
26.	 Removal of the 3.5" Tape Drive Panel does not require any tool a. Press the blue release le pushing it forward to rele and then sliding it out fro front of the system. b. Discard the tape drive for panel in the appropriate Recycling Bin. 	s. ever and ase it m the filler			
27.	 Removal of the 2.5" HDD Backy requires a #2 Philips screwdriver and un thumbscrew from backpl. d. Shift backplane towards Control Panel side of the enclosure. e. Carefully remove the bastraight out towards you. f. Discard the backplane appropriate Recycling 	er. screw ane. the ckplane in the			



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30.	 Removal of the motherboard rephillips #2 screwdriver. a. Unscrew all remaining somotherboard. b. Lift motherboard straight server. c. Discard the Motherboard screws in the appropriation Recycling Bin. 	out of rd and			
31.	 Removal of any remaining front panels present does not require tools. a. Carefully pry the panel o both sides from the front system. b. Discard all filler panel i appropriate Recycling 	e any ut from of the n the			
32.	 Removal of any I/O Expansion I Filler Panels does not require a a. Squeeze the sides of the expansion module filler p to disengage it from the s system back panel and r it. b. Discard the filler panels appropriate Recycling 	ny tools. I/O banel(s) server emove	Filler Panels		

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E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)



Recycling/Material Code	Important Information		
Material /Components, which must be removed and treated separately			
Lithium Battery	Battery free of hazardous substances,		
	installed in socket on the motherboard		
Lithium Ion RAID Battery Backup	Battery is RoHS 5/6, installed beside the		
	active mid-plane		
RAID Activation Key	RAID Activation Key free of hazardous substances, installed in socket on the mid- plane		

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** LCD-Display	LCD control board background lighting				
	contains Hg				
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser,				
	Power Sur	Power Supply, Active Mid-Plane,			
		Backplane, RAID DIMM, Power			
	Distributio	Distribution Board, IO Expansion Module,			
	Remote M	Remote Management Module, Bridge			
	Board, & F	Board, & Front Panel Control Board			
Disk Drives	Mounted of	Mounted on disk carrier			

Material /Components, which can disturb certain recycling processes			
Copper	Fansink		
Material /Components, through which benefits can normally be achieved			
Cold Rolled Steel	Fixed cover, PCI bracket, & chassis		
* ABS	Bezel, Control Panel Bezel, Cable Guide,		
	Power Distribution Board Cover, Fan		
	Assembly, & Air Baffle		
Cables	Distributed in device & power cord		
Fans	Fan Assembly		
Special notes			

** LCD display background lights contain Hg.
* Flame retardant of plastics **do not** contain PBB and PBDE.

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Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>
Scope of information sheet:	< product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	Lithium battery L located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm2	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector contacts
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention *****	NONE
(diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE

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= arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/(EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

*** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

**** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

***** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.